

Electronic Filing System (EFS) Data
Electronic Patent Application Submission
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EFS ID: 14959
Application ID: 10063572
Title of Invention: WAFER LEVEL PACKAGING AND CHIP STRUCTURE
First Named Inventor: Chi-Hsing Hsu
Domestic/Foreign Application: Domestic Application
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Effective Receipt Date: 2002-05-03 
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TRANSMITTAL FORM

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Attorney Docket
Number:

8289-US-
PA

Submission Type: Utility Patent
Filing

WAFER LEVEL PACKAGING AND CHIP STRUCTURE

First Named Inventor: Mr. Chi-Hsing Hsu

SUBMITTED BY

Name: Miss BELINDA LEE
Registration Number: 46863
Electronic Signature Mark: /BL Date Signed: 20020503

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I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.

Attached Files:

declaration	8289declaration1.tif
declaration	8289declaration2.tif
bibd-transmittal	8289usapds.xml
patent-assignments	8289usasgn.xml

fee-transmittal 8289usfee.xml
specification 8289usf.xml

Attached Image File(s):

8289declaration1.tif

8289declaration2.tif

Comments:

2020-03-23 10:30:00 AM

COMBINED DECLARATION AND POWER OF ATTORNEY

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name and that I believe I am an original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

WAFER LEVEL PACKAGING AND CHIP STRUCTURE

the specification of which

is attached hereto.

was filed on _____
as Application Serial No. _____ and was amended on _____.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the patentability of this application in accordance with Title 37, Code of Federal Regulations, § 1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s):

Number	Country	Date Filed(yyyy/mm/dd)	Yes	No
90132737	Taiwan, R.O.C.	2001/12/28	<input checked="" type="checkbox"/>	

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

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COMBINED DECLARATION AND POWER OF ATTORNEY CONTINUED

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patents issued thereon.

Signature: Chi-Hsing Hsu Date: Jan. 22, 2002

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FEE TRANSMITTAL

Electronic Version 1.1.0

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Patent fees are subject to annual revisions on or about October 1st of each year.

Large Entity

TOTAL FEES AUTHORIZED: \$ 864

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Credit Card Number: 3109
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BASIC FILING FEE

Fee Description	Fee Code	Fee Paid
Utility Filing Fee	101	\$ 740

Subtotal For Basic Filing Fee: \$ 740

EXTRA CLAIM FEES

	Fee Code	Fee	Extra Claims	Fee Paid
Total Claims: 20	103	\$ 18	0	\$ 0
Independent Claims: 4	102	\$ 84	1	\$ 84

Subtotal For Extra Claims Fees: \$ 84

ADDITIONAL FEES

Fee Description	Number	Quantity	Fee Code	Amount	Fee Paid
Recording Each Patent Assignment Per Property Fee	00000000	1	581	\$ 40	\$ 40

Subtotal For Additional Fees: \$ 40